Material Declaration Report

PERICOM Semiconductor Corporation
www.pericom.com

Package Type:	FQFP 208L (28x28mm)
Pericom Package Code:	MA208(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	5517.500
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	3
Peak Body Temp (C):	245C
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	8/19/2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	4922.118	ASE-Malaysia	Silica Fused	60676-86-0	88.000	4331.4636
		and	Epoxy Resin	Proprietary	5.000	246.1059
		GTK	Phenolic Resin	Proprietary	4.500	221.4953
			Epoxy, Cresol Novolac	29690-82-2	2.000	98.4424
			Carbon Black	1333-86-4	0.500	24.6106
			Copper	7440-50-8	95.140	517.3962
LEADFRAME	543.826		Nickel	7440-02-0	3.200	17.4024
			Silver	7440-22-4	0.760	4.1331
			Silicon	7440-21-3	0.725	3.9427
			Magnesium	7439-95-4	0.175	0.9517
SILICON DIE	15.448		Silicon (Si)	7440-21-3	99.192	15.3234
			Non-hazardous Metal	Proprietary	0.808	0.1248
DIE ATTACH EPOXY	2.808	ASE	Silver	7440-22-4	84.000	2.3591
			Epoxy Resin	Proprietary	8.000	0.2247
			gamma-Butyrolactone	96-48-0	8.000	0.2247
		GTK	Silver	7440-22-4	67.000	1.8816
			Epoxy Resin	Proprietary	15.000	0.4213
			Aliphatic anhydride	Proprietary	8.000	0.2247
			2-Butoxyethyl acetate	112-07-2	5.000	0.1404
			Polymeric material	Proprietary	5.000	0.1404
GOLD WIRE	1.204		Gold(Au)	7440-57-5	99.990	1.2035
			Impurities	-	0.010	0.0001
SOLDER PLATING	32.096		Tin (Sn)	7440-31-5	99.990	32.0928
			Impurity	-	0.010	0.0032

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
Device	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb	Hg	Cr+6	Cd	PBB	PBDE
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.